



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC360N15NS3 G	Issued	17. February 2022
MA#	MA005698924		
Package	PG-TDSON-8-1	Weight*	120.87 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.357	1.95	1.95	19498	19498
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		94	
	non noble metal	iron	7439-89-6	0.038	0.03		313	
	non noble metal	copper	7440-50-8	37.762	31.22	31.26	312410	312817
wire	non noble metal	copper	7440-50-8	0.073	0.06	0.06	601	601
encapsulation	organic material	carbon black	1333-86-4	0.084	0.07		692	
	plastics	epoxy resin	-	5.939	4.91		49133	
	inorganic material	silicondioxide	60676-86-0	35.800	29.62	34.60	296184	346009
leadfinish	non noble metal	tin	7440-31-5	1.452	1.20	1.20	12010	12010
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1369	1369
solder	non noble metal	tin	7440-31-5	0.045	0.04		372	
	noble metal	silver	7440-22-4	0.056	0.05		465	
	non noble metal	lead	7439-92-1	2.146	1.78	1.87	17753	18590
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	iron	7439-89-6	0.022	0.02		185	
	noble metal	silver	7440-22-4	1.289	1.07		10668	
	non noble metal	copper	7440-50-8	22.292	18.44	19.54	184423	195331
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		94	
	non noble metal	copper	7440-50-8	11.320	9.37	9.38	93653	93775
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com